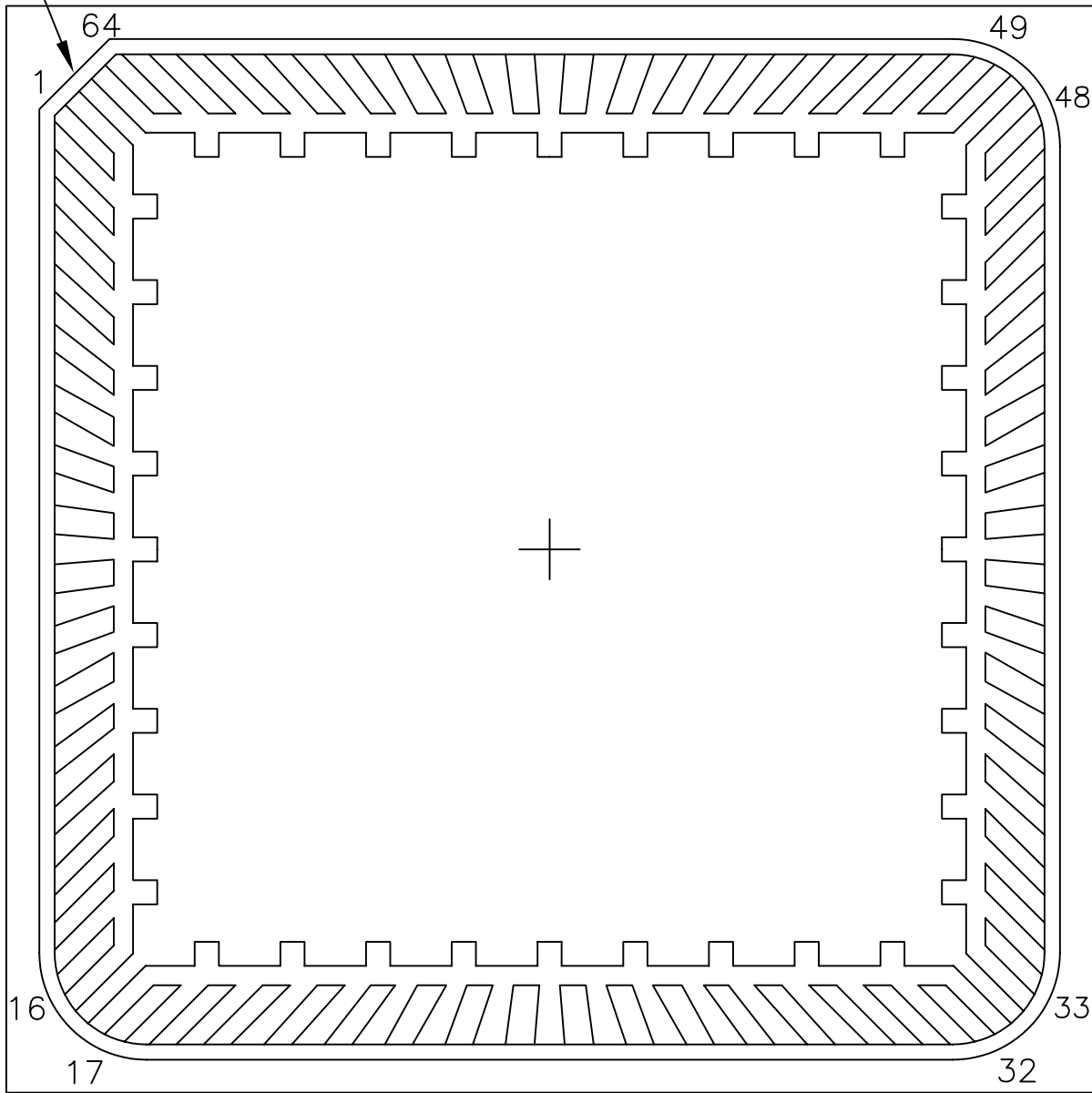


PIN #1 IDENTIFIER



DEVICE TYPE:				<p align="center">SEMPAC, INC. Open-Pak™ Technologies www.sempac.com 568 E. WEDDELL DRIVE, SUITE 5 SUNNYVALE, CALIFORNIA 94089 PHONE: (408) 400-9002 FAX: (408) 400-9006</p>							
CUSTOMER:			DIE SIZE:								
WIRE TYPE/ SIZE:			NO. OF WIRES:								
		REVISIONS				<p align="center">64 Lead 9mm x 9mm MLP Open-Pak Bonding Diagram</p>					
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETER DO NOT SCALE DRAWING		ECN NO.	DATE	DESCRIPTION	APPROVED						
		10639	04/01/06	INITIAL RELEASE	D.BENANDO						
DRAWN BY	W. GRIFFITTS	DATE	04/01/06	PACKAGE SIZE:	9.00mm x 9.00mm	SIZE	PART NO.	MLP9X9-64-OP-01	REV	1	
APP BY	P. FLASKERUD	DATE	04/01/06	DIE PAD SIZE:	6.900mm x 6.900mm	SCALE	18X	CAD FILE	MLP9X9-64-OP-01-B-R1.DWG	SHEET	1 OF 1